

LM337L 3-Terminal Adjustable Regulator

Check for Samples: LM337L

FEATURES

- Adjustable output down to 1.2V
- Guaranteed 100mA output current
- Line regulation typically 0.01%/V
- Load regulation typically 0.1%
- · Current limit constant with temperature

- Eliminates the need to stock many voltages
- Standard 3-lead transistor package
- 80 dB ripple rejection
- Output is short circuit protected
- Available in the 6-Bump micro SMD package
- See AN-1112 for micro SMD considerations

DESCRIPTION

The LM337L is an adjustable 3-terminal negative voltage regulator capable of supplying 100mA over a 1.2V to 37V output range. It is exceptionally easy to use and requires only two external resistors to set the output voltage. Furthermore, both line and load regulation are better than standard fixed regulators. Also, the LM337L is packaged in a standard TO-92 transistor package which is easy to use.

In addition to higher performance than fixed regulators, the LM337L offers full overload protection. Included on the chip are current limit, thermal overload protection and safe area protection. All overload protection circuitry remains fully functional even if the adjustment terminal is disconnected.

Normally, only a single 1μ F solid tantalum output capacitor is needed unless the device is situated more than 6 inches from the input filter capacitors, in which case an input bypass is needed. A larger output capacitor can be added to improve transient response. The adjustment terminal can be bypassed to achieve very high ripple rejection ratios which are difficult to achieve with standard 3-terminal regulators.

Besides replacing fixed regulators, the LM337L is useful in a wide variety of other applications. Since the regulator is "floating" and sees only the input-to-output differential voltage, supplies of several hundred volts can be regulated as long as the maximum input-to-output differential is not exceeded.

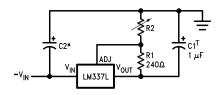
Also, it makes an especially simple adjustable switching regulator, a programmable output regulator, or by connecting a fixed resistor between the adjustment and output, the LM337L can be used as a precision current regulator. Supplies with electronic shutdown can be achieved by clamping the adjustment terminal to ground which programs the output to 1.2V where most loads draw little current.

The LM337L is available in a standard TO-92 transistor package, SO-8 surface mount package, and in our new 12 mil diameter bump micro SMD package. The LM337L is rated for operation over a −25°C to +125°C range.

For applications requiring greater output current in excess of 0.5A and 1.5A, see LM137 series data sheets. For the positive complement, see series LM117 and LM317L data sheets.

Typical Application

Figure 1. 1.2V-25V Adjustable Regulator



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Connection Diagrams

3-Pin TO92



Figure 2. Bottom View

8-Pin SOIC

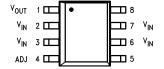


Figure 3. Top View

Figure 4. 6-Bump micro SMD

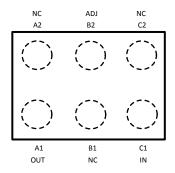
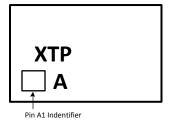


Figure 5. micro SMD Laser mark





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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Absolute Maximum Ratings (1)

-	
Power Dissipation	Internally Limited
Input-Output Voltage Differential	40V
Operating Junction Temperature Range	−25°C to +125°C
Storage Temperature	−55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	300°C
Plastic Package (Soldering 4 sec.)	260°C
ESD Rating	1.5kV ⁽²⁾

^{(1) &}quot;Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.

⁽²⁾ Human body model, $1.5k\Omega$ in series with 100pF.



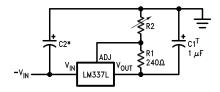
Electrical Characteristics (1)

Parameter	Conditions	Min	Тур	Max	Units	
Line Regulation	$T_A = 25^{\circ}C, 3V \le V_{IN} - V_{OUT} \le 40V,$		0.01	0.04	%/V	
	(2)					
Load Regulation	$T_A = 25^{\circ}C, 5mA \le I_{OUT} \le I_{MAX},$ (2)		0.1	0.5	%	
Thermal Regulation	T _A = 25°C, 10ms Pulse		0.04	0.2	%/W	
Adjustment Pin Current			50	100	μA	
Adjustment Pin Current Change	5mA ≤ I _L ≤ 100mA		0.2	5	μA	
	$3V \le V_{IN} - V_{OUT} \le 40V$					
Reference Voltage	$3V \le V_{IN} - V_{OUT} \le 40V$, (3)	1.20	1.25	1.30	V	
	10mA ≤ I _{OUT} ≤ 100mA, P ≤ 625mW					
Line Regulation	$3V \le V_{IN} - V_{OUT} \le 40V$, (2)		0.02	0.07	%/V	
Load Regulation	5mA ≤ I _{OUT} ≤ 100mA, ⁽²⁾	2)			%	
Temperature Stability	$T_{MIN} \le T_j \le T_{MAX}$		0.65		%	
Minimum Load Current	V _{IN} − V _{OUT} ≤ 40V		3.5	5	mA	
	$3V \le V_{IN} - V_{OUT} \le 15V$		2.2	3.5	mA	
Current Limit	$3V \le V_{IN} - V_{OUT} \le 13V$	100	200	320	mA	
	V _{IN} - V _{OUT} = 40V	25	50	120	mA	
Rms Output Noise, % of V _{OUT}	$T_A = 25^{\circ}C, 10Hz \le f \le 10kHz$		0.003		%	
Ripple Rejection Ratio	$V_{OUT} = -10V$, F = 120 Hz, $C_{ADJ} = 0$		65		dB	
	$C_{ADJ} = 10 \mu F$	66	80		dB	
Long-Term Stability	T _A = 125°C		0.3	1	%	

- (1) Unless otherwise specified, these specifications apply $-25^{\circ}\text{C} \le \text{T}_{\text{J}} \le +\ 125^{\circ}\text{C}$ for the LM337L; $|V_{\text{IN}} V_{\text{OUT}}| = 5V$ and $I_{\text{OUT}} = 40\text{mA}$. Although power dissipation is internally limited, these specifications are applicable for power dissipations up to 625 mW. I_{MAX} is 100mA.
- (2) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.
- (3) Thermal resistance of the TO-92 package is 180°C/W junction to ambient with 0.4" leads from a PC board and 160°C/W junction to ambient with 0.125" lead length to PC board. The M package θ_{JA} is 180°C/W in still air. The 6-Bump micro SMD package θ_{JA} is 290°C/W in still air.

Typical Applications

Figure 6. 1.2V-25V Adjustable Regulator



Full output current not available at high input-output voltages

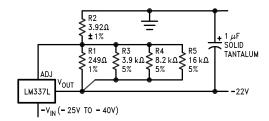
$$-V_{OUT} = -1.25V \left(1 + \frac{R2}{240\Omega}\right)$$

 $\dagger C1 = 1\mu F$ solid tantalum or $10\mu F$ aluminum electrolytic required for stability

*C2 = 1µF solid tantalum is required only if regulator is more than 4" from power supply filter capacitor



Figure 7. Regulator with Trimmable Output Voltage



Trim Procedure:

- —If V_{OUT} is −23.08V or bigger, cut out R3 (if smaller, don't cut it out).
- —Then if V_{OUT} is −22.47V or bigger, cut out R4 (if smaller, don't).
- —Then if V_{OUT} is $\neg 22.16V$ or bigger, cut out R5 (if smaller, don't).

This will trim the output to well within 1% of -22.00 V_{DC} , without any of the expense or trouble of a trim pot (see LB-46). Of course, this technique can be used at any output voltage level.

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	•	Op Temp (°C)		Samples
LM337LM	ACTIVE	SOIC	Diawing	8	95	(2) TBD	CU SNPB	(3) Level-1-235C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM337 LZ	Samples
LM337LZ/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM337 LZ	Samples
LM337LZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM337 LZ	Samples
LM337LZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	-25 to 100	LM337 LZ	Samples

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

9-Feb-2013

(4) Only one of markings shown within the brackets will appear on the physical device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM337LMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM337LMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM337LMX	SOIC	D	8	2500	349.0	337.0	45.0
LM337LMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0

D (R-PDSO-G8)

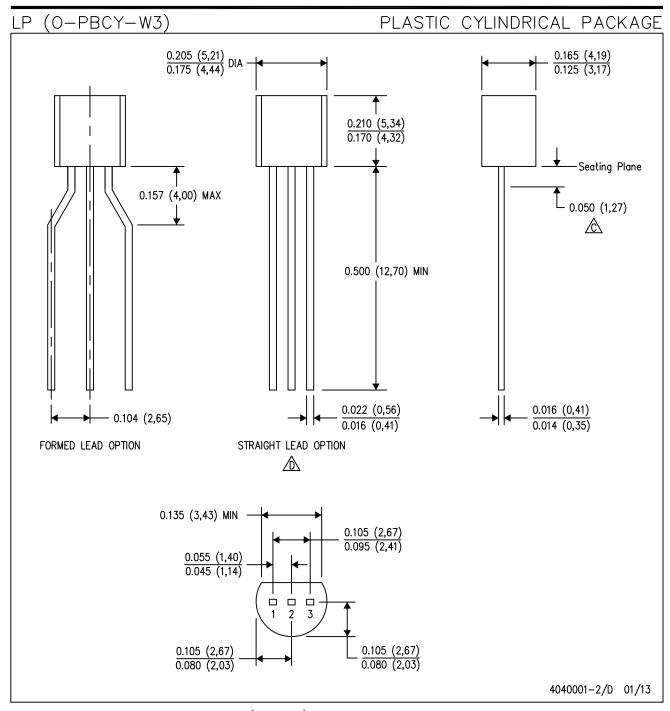
PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Lead dimensions are not controlled within this area.

Falls within JEDEC TO-226 Variation AA (TO-226 replaces TO-92).

E. Shipping Method:

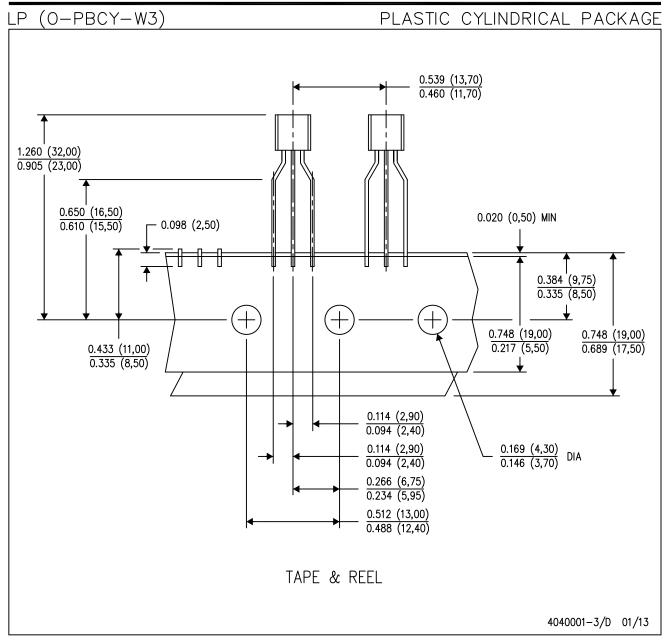
Straight lead option available in either bulk pack or tape & reel.

Formed lead option available in tape & reel or ammo pack.

Specific products can be offered in limited combinations of shipping mediums and lead options.

Consult product folder for more information on available options.





NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Tape and Reel information for the Formed Lead Option package.

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